SBA4089Z



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DCto5GHz, CASCADABLE InGaP/GaAs HBT MMIC AMPLIFIER





Product Description

RFMD's SBA4089Z is a high performance InGaP/GaAs Heterojunction Bipolar Transistor MMIC Amplifier. A Darlington configuration designed with InGaP process technology provides broadband performance up to 5GHz with excellent thermal performance. The heterojunction increases breakdown voltage and minimizes leakage current between junctions. Cancellation of emitter junction non-linearities results in higher suppression of intermodulation products. Only a single positive supply voltage, DC-blocking capacitors, a bias resistor, and an optional RF choke are required for operation.



Features

- IP3=33.5dBm at 1950MHz
- P_{OUT}=13.3dBm at -45dBc ACP IS-95 1950MHz
- Robust 1000V ESD, Class 1C
- Operates From Single Supply
- Patented Thermal Design

Applications

- PA Driver Amplifier
- Cellular, PCS, GSM, UMTS
- IF Amplifier
- Wireless Data, Satellite Terminals

Paramatar	Specification			Unit	O a u di Ai a u	
Parameter	Min.	Тур.	Max.	Unit	Condition	
Small Signal Gain	13.5	15.0	16.5	dB	850MHz	
	13.1	14.6	16.1	dB	1950MHz	
Output Power at 1dB Compression		19.2		dBm	850MHz	
	17.5	19.0		dBm	1950MHz	
Output Third Order Intercept Point		36.5		dBm	850MHz	
	31.5	33.5		dBm	1950MHz	
Output Power		13.3		dBm	1950 MHz, -45 dBc ACP IS-95 9 Forward Channels	
Bandwidth		4400		MHz	Return Loss>10dB	
Input Return Loss	14.0	21.0		dB	1950MHz	
Output Return Loss	11.0	15.0		dB	1950MHz	
Noise Figure		4.8	5.8	dB	1950MHz	
Device Operating Voltage	4.8	5.0	5.4	V		
Device Operating Current	72	80	88	mA		
Thermal Resistance (junction to lead)		70		°C/W		

Test Conditions: V_S=8V, I_D=80mA Typ., OIP₃ Tone Spacing=1MHz, P_{OUT} per tone=0dBm, R_{BIAS}=39Ω, T_L=25°C, Z_S=Z_L=50Ω

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Absolute Maximum Ratings

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Parameter	Rating	Unit
Device Current (I _D)	130	mA
Device Voltage (V _D)	6	V
RF Input Power	+17	dBm
Junction Temp (T _J)	+150	°C
Operating Temp Range (T_L)	-40 to +85	°C
Storage Temp	+150	°C
Operating Dissipated Power	0.65	W
Moisture Sensitivity Level	MSL 2	

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation, the device voltage and current must not exceed the maximum operating values specified in the table on page one. Bias Conditions should also satisfy the following expression:

 $I_D V_D < (T_J - T_L) / R_{TH}$, j-l and $T_L = T_{LEAD}$

Parameter	Unit	100MHz	500 MHz	850 MHz	1950MHz	2400 MHz	3500 MHz
Small Signal Gain	dB	15.3	15.3	15.0	14.6	14.3	13.2
Dutput Third Order Intercept Point	dBm	37.1	36.2	36.5	33.5	32.7	30.5
Output Power at 1dB Compression	dBm	19.0	19.1	19.0	19.0	18.3	16.3
Input Return Loss	dB	47	33	29	21	17.5	13.3
Output Return Loss	dB	22	22	21	15	13.3	12
Reverse Isolation	dB	18	18	18.7	19	19	19
Noise Figure	dB	4.1	4.3	4.2	4.8	-	-

Test Conditions: V_S=8V, I_D=80mA Typ., OIP_3 Tone Spacing=1MHz, P_{OUT} per tone=0dBm, R_{BIAS}=39\Omega, T_L=25°C, Z_S=Z_L=50\Omega







Frequency (GHz)

Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical perfor-mance or functional operation of the device under Absolute Maximum Rating condi-tions is not implied.

RoHS status based on EUDirective 2002/95/EC (at time of this document revision).

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Basic Application Circuit



Mounting Instructions:

1. Solder the copper pad on the backside of the device package to the ground plane.

2. Use a large ground pad area under device pins 2 and 4 with many plated through-holes as shown.

3. We recommend 1 or 2 ounce copper. Measurements for this data sheet were made on a 31mil thick FR-4 board with 1 ounce copper on both sides.

Reference Designator	500MHz	850MHz	1950 MHz	2400 MHz	3500 MHz		
C _B	220pF	100pF	68pF	56pF	39 pF		
C _D	100pF	68 p F	22pF	22pF	15 pF		
L _C	68 nH	33 nH	22nH	18nH	15nH		
Recommended Bias Resistor Values for $I_D = 80 \text{ mA}$, $R_{BIAS} = (V_S - V_D) / I_D$							
Supply Voltage (V _S)	7.5V	8V	10V	12V			
R _{BIAS}	33Ω	39Ω	68Ω	91Ω			

Application Circuit Element Values

Note: $\mathsf{R}_{\mathsf{BIAS}}$ provides DC bias stability over temperature.





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Pin	Function	Description
1	RF IN	RF input pin. This pin requires the use of an external DC-blocking capacitor chosen for the frequency of opera- tion.
2, 4	GND	Connection to ground. Use via holes for best performance to reduce lead inductance as close to ground leads as possible.
3	RF OUT/BIAS	RF output and bias pin. DC voltage is present on this pin, therefore a DC-blocking capacitor is necessary for proper operation.



PCB Pad Layout





Package Drawing

Dimensions in inches (millimeters) Refer to drawing posted at www.rfmd.com for tolerances.





Part Identification



Ordering Information

Part Number	Reel Size	Devices/Reel
SBA-4089	7"	1000
SBA-4089Z	7"	1000